ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® International and Pan	C, Bannockb	ourn, Illinois. A	Il rights reserved u ntions.	nder both	This docum level parts, t	ent is a declarat the declaration e	on of the suncompasse	ubstances s all lowe	within the manufacture within the manufacture within the materials for w	rer listed which the	item. Note: i manufacturer	f the item is an as has engineering	ssembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distr				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and N	als and Mfg Information				
Supplier Information														
Company name* Comp			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2024-0	2024-05-21			
Contact Name Title - Contact			ct			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product Envi			Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repres			esentative			Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards Product Er			ct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version		Manufacturing Site		Weight*	UOM	Unit Type	
	FDMS86	FDMS86255 FET 150		ET 150V 12.4 mOhm PQFN56		2024-05-21			PBB		122.136	mg	Each	
Manufacturing Proccess Informat	ion						·						·	
Terminal Plating / Grid Array Ma	Array Material Terminal Base		Alloy J	J-STD-020 MSL Rating		Peak Proc	Peak Process Body Temperatu		ure Max Time at Peak Tempera		ature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy		1	1		260		С	30	seco	nds 3				
Comments														
level 1 - maximum time at peak temperatu	re during sol	ldering is 10-3	0 seconds											
For more information regarding material (composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company that agreement, will be the sole and exclusive	ase indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, mium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part tains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall compass all such components.Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best for the RoHS Directive. mpany acknowledges that Supplier completes this form.Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. mpany acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not ependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the tification in this paragraph. If the Company and the Supplier of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the tranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.0229	mg
			Supplier	Iron (Fe)	7439-89-6		0.4489	mg
			Supplier	Copper (Cu)	7440-50-8		18.6225	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0057	mg
Die	2.54	mg	Supplier	Silicon (Si)	7440-21-3		2.54	mg
Lead Frame	46.436	mg	Supplier	Silver (Ag)	7440-22-4		0.065	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0464	mg
			Supplier	Iron (Fe)	7439-89-6		0.9752	mg
			Supplier	Copper (Cu)	7440-50-8		45.303	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0464	mg
Mold Compound-Black	42.7	mg		Proprietary	proprietary data		3.416	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2135	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.0705	mg
Plating	8.33	mg	Supplier	Tin (Sn)	7440-31-5		8.33	mg
Solder Paste	3.017	mg	Supplier	Silver (Ag)	7440-22-4		0.0754	mg
			А	Lead (Pb)	7439-92-1	7a	2.8812	mg
			Supplier	Tin (Sn)	7440-31-5		0.0603	mg
Wire Bond - Cu	0.013	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0128	mg